

In re the Application of:
 KANDA
 Serial No. 09/607,219
 Filed: June 30, 2000
 For: SEMICONDUCTOR DEVICES AND
 METHODS OF FABRICATING
 THE SAME



Group Art Unit: 2814
 Examiner: Quach, T.

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ASSISTANT COMMISSIONER OF PATENTS
 Washington, D.C. 20231

Sir:

Transmitted herewith is an Amendment and a Request for Continued Examination in the above-identified application.

- Small entity status of this application under 37 CFR 1.9 and 1.27 has been established by a verified statement previously submitted.
- A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is enclosed.
- No additional fee is required.

The fee has been calculated as shown below:

	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST NO PREVIOUSLY PAID FOR	PRESENT EXTRA RATE	ADDIT. FEE OR +	ADDIT. RATE OR \$	ADDIT. FEE x 18 OR x 84 OR + 280 OR TOTAL \$0
TOTAL	25	MINUS	47	=	0	x \$0 OR x 18 \$0
INDEP CLAIMS *	3	MINUS	5	=	0	x \$0 OR x 84 \$0
	<u>FIRST PRESENTATION OF MULTIPLE DEP. CLAIM</u>				+ \$0 OR + 280 \$0	
				TOTAL	\$0 OR	TOTAL \$0

Please charge Deposit Account No. 50-0585 the amount of \$____ to cover the extension fee and also the amount of \$____ to cover the claim fee. A duplicate copy of this sheet is enclosed.

A check in the amount of \$ 930 to cover the extension fee is enclosed.

A check in the amount of \$____ to cover the filing fee for additional claims is enclosed.

A check in the amount of \$____ to cover the petition fee is enclosed.

A check in the amount of \$ 750 to cover the RCE fee is enclosed.

The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. No. 50-0585. A duplicate of this sheet is enclosed.

Any filing fees under 37 CFR 1.16 for the presentation of extra claims.

Any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,

Dated: Jan. 31, 2003

Alan S. Raynes

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I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on January 31, 2003.

Alan S. Raynes

1/31/03

Date



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:) Group Art Unit: 2814
KANDA)
Serial No. 09/607,219) Examiner: Quach, T.
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AMENDMENT

Box RCE
Commissioner for Patents
Washington, DC 20231

Dear Sirs:

In response to the Office Action dated July 31, 2002, the response being due by January 31, 2003 by the enclosed Petition for Extension of Time, applicants have filed a Request for Continued Examination and also request entry and consideration of the following.

IN THE CLAIMS:

Please cancel claims 80-51 without prejudice.

Please amend claims 48-49, 52-56, 58, 61-68, 70 and 72 as follows:

48. (amended) A method of fabricating a semiconductor device comprising:
forming a pad;
forming a protective insulating region on the pad including first and second insulating layers, the first insulating layer being in direct contact with the pad and the second insulating layer being in direct contact with the first insulation layer; the second insulating layer comprising silicon nitride;
forming a mask layer on the protective insulating region in direct contact with a surface of the second insulating layer, the second insulating layer being positioned between the first